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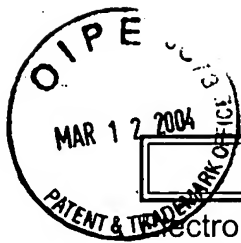
Electronic Filing System (EFS) Data
Electronic Patent Application Submission
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EFS ID: 57015
Application ID: 10706468
Title of Invention: SEMICONDUCTOR PACKAGE
WITH CHAMFERED CORNERS
AND METHOD OF
MANUFACTURING THE SAME
First Named Inventor: Sung Yang
Domestic/Foreign Application: Domestic Application
Filing Date: 2003-11-12
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Statement
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Confirmation number: 6744
Attorney Docket Number: AMKOR095A




Total Fees Authorized:

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**TRANSMITTAL**

Electronic Version v1.1
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Title of Invention	SEMICONDUCTOR PACKAGE WITH CHAMFERED CORNERS AND METHOD OF MANUFACTURING THE SAME									
Application Number: 10/706468 										
Date: 2003-11-12										
First Named Applicant: Sung Jin Yang										
Confirmation Number: 6744										
Attorney Docket Number: AMKOR095A										
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<table border="1"><thead><tr><th>Submitted by:</th><th>Elec. Sign.</th><th>Sign. Capacity</th></tr></thead><tbody><tr><td>Mark B. Garred Registered Number: 34,823</td><td>/mbg/</td><td>Attorney</td></tr></tbody></table>			Submitted by:	Elec. Sign.	Sign. Capacity	Mark B. Garred Registered Number: 34,823	/mbg/	Attorney		
Submitted by:	Elec. Sign.	Sign. Capacity								
Mark B. Garred Registered Number: 34,823	/mbg/	Attorney								
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	us-ids.dtd									
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Comments										



ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

Title of
Invention

SEMICONDUCTOR PACKAGE WITH CHAMFERED
CORNERS AND METHOD OF MANUFACTURING THE
SAME

Application Number: 10/706468
Confirmation Number: 6744
First Named Applicant: Sung Yang
Attorney Docket Number: AMKOR095A
Art Unit: 2811

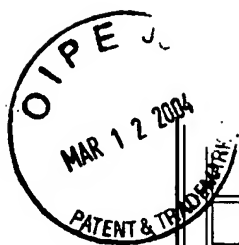


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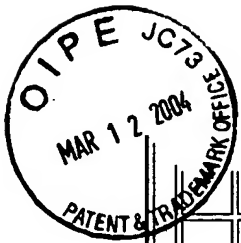
US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

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Note: Applicant is not required to submit a paper copy of cited US Published Applications

init	Cite.No.	Pub. No.	Date	Applicant	Kind	Class	Subclass
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	10	20030073265	2003-04-17	HU ET AL.			

Signature

Examiner Name	Date